

Application No. 10/660,687

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*AMENDMENTS TO THE CLAIMS*

This listing of claims replaces all prior versions, and listings, of claims in the application.

1. (Currently Amended) A system for planarizing or polishing a composite substrate comprising (i) a polishing composition comprising (a) about 0.5 wt.% ~~or more to~~ about 10 wt.% of a source of fluoride ions, (b) about 1 wt.% ~~or more to~~ about 10 wt.% of an amine, (c) about 0.1 wt.% or more of a base, and (d) water, and (ii) an abrasive.
2. (Original) The system of claim 1, wherein the system has a pH of about 7-14.
3. (Original) The system of claim 1, wherein the abrasive is selected from the group consisting of alumina, silica, titania, ceria, zirconia, germania, magnesia, coformed products thereof, and mixtures thereof.
4. (Original) The system of claim 3, wherein the abrasive is silica.
5. (Original) The system of claim 1, wherein the abrasive is present in the polishing composition in a concentration of about 0.1 wt.% or more.
6. (Original) The system of claim 1, wherein the abrasive is fixed in or on a polishing pad.
7. (Original) The system of claim 1, wherein the fluoride ions are from a source of fluoride ions selected from the group consisting of fluoride salts, fluoride acids, fluoride metal complexes, and combinations thereof.
8. (Original) The system of claim 1, wherein the amine is an amino alcohol.
9. (Original) The system of claim 8, wherein the amine is 2-dimethylamino-2-methyl-1-propanol.
10. (Original) The system of claim 1, wherein the base is selected from the group consisting of inorganic hydroxide bases and carbonate bases.

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11. (Original) The system of claim 10, wherein the base is selected from the group consisting of potassium hydroxide, sodium hydroxide, ammonium hydroxide, cesium hydroxide, sodium carbonate, and mixtures thereof.

12. (Original) The system of claim 1, wherein the system further comprises a quaternary ammonium compound.

13. (Original) The system of claim 1, wherein the system has a polishing selectivity of oxide:nitride of about 2:1 or more.

14. (Original) The system of claim 1, wherein the system comprises a cationic species that reduces nitride removal from the composite substrate.

15. (Original) The system of claim 1, wherein the fluoride ions comprise less than about 100% active fluoride ions.

16. (Original) The system of claim 1, wherein the system has a free alkalinity value of about 0.001-0.15 mol/l.

17. (Original) The system of claim 1, wherein the system has a total alkalinity value of about 0.005-0.2 mol/l.

18-42. (Canceled)